



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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1750
7/c 11/18/02
~~11/18/02~~

In re Application of:

William E. Bernier et al.

Serial No.: 09/687,524

Art Unit: 1725

Filed: October 12, 2000

Examiner: Johnson, J.

For: SOLDER PROTECTIVE
COATING AND FLUXLESS
JOINING OF FLIP CHIP
DEVICES ON LAMINATES
WITH PLATED SOLDER.

Atty Docket: END920000034US1
(20135/0311)

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RESPONSE AND AMENDMENT UNDER 37 CFR § 1.116

ATTN: BOX AF

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action dated September 11, 2002, please amend the above-identified application as follows:

IN THE CLAIMS:

Kindly amend claim 1 as follows:

1. (Twice amended) A method of protecting tin solderable surfaces comprising:
providing a solderable surface having tin oxide thereon;
providing a gas-phase ambient comprising a complexing agent;
applying said complexing agent from said gas-phase to said solderable
surface;

forming a protected solderable surface by forming a reaction product with
said tin oxide and said complexing agent, wherein said reaction product decomposes to a